TYPICAL DEVICE CHARACTERISTICS

MAXIMUM RATINGS @ 25°C Unless Otherwise Specified			
PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power (tp = 8/20µs) - See Figure 1	P_{PP}	1000	Watts
Operating Temperature	T_A	-55 to 150	°C
Storage Temperature	T_{STG}	-55 to 150	°C

ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified							
PART NUMBER	DEVICE MARKING	RATED STAND-OFF VOLTAGE V_{WM} VOLTS	MINIMUM BREAKDOWN VOLTAGE @ 1mA $V_{(BR)}$ VOLTS	MAXIMUM CLAMPING VOLTAGE (Fig. 2) @ IP = 1A V_C VOLTS	MAXIMUM CLAMPING VOLTAGE (Fig. 2) @ 8/20µs V_C @ I_{PP}	MAXIMUM LEAKAGE CURRENT @V_{WM} I_D µA	TYPICAL CAPACITANCE @0V, 1MHz C pF
PSD05HP	P	5.0	6.0	9.8	15.0V @ 72.0A	20	800
PSD10HP	P10	10.0	11.0	16.2	25.0V @ 45.0A	2	500
PSD12HP	P12	12.0	13.3	19.1	32.0V @ 34.0A	2	440

TYPICAL DEVICE CHARACTERISTICS

FIGURE 1
PEAK PULSE POWER VS PULSE TIME

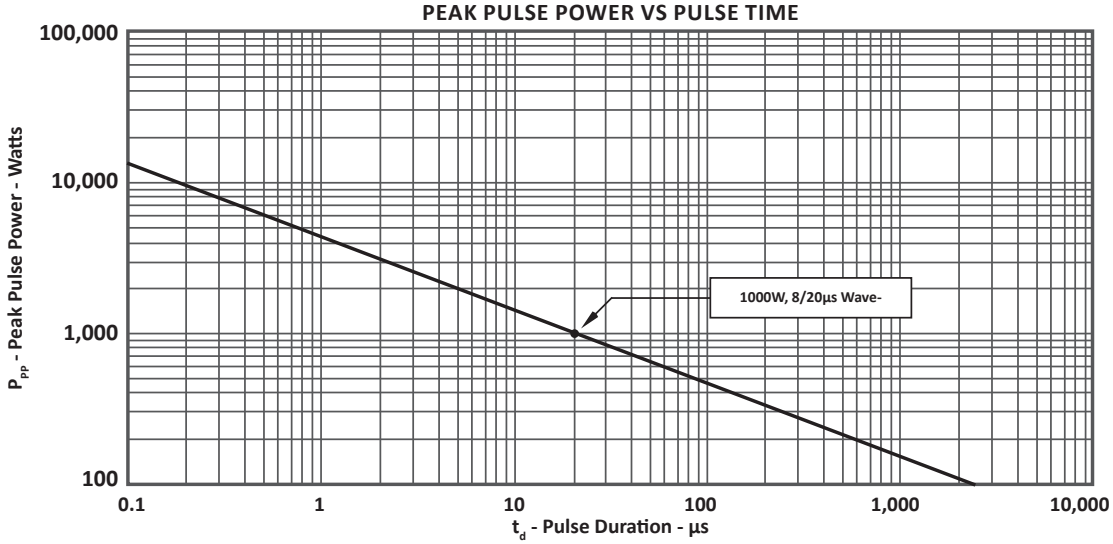


FIGURE 2
PULSE WAVE FORM

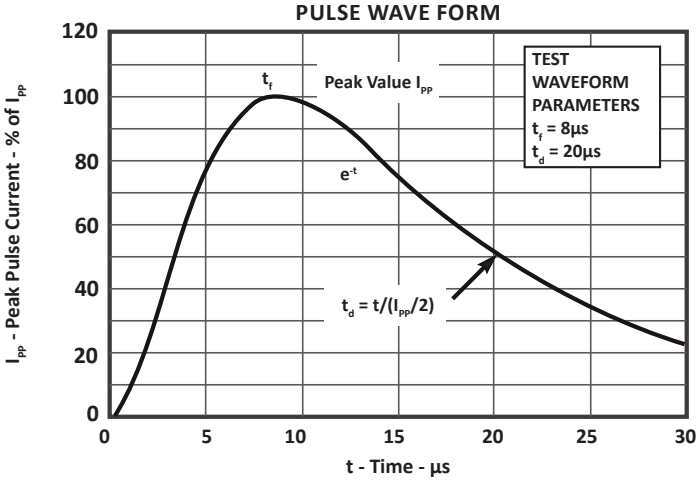
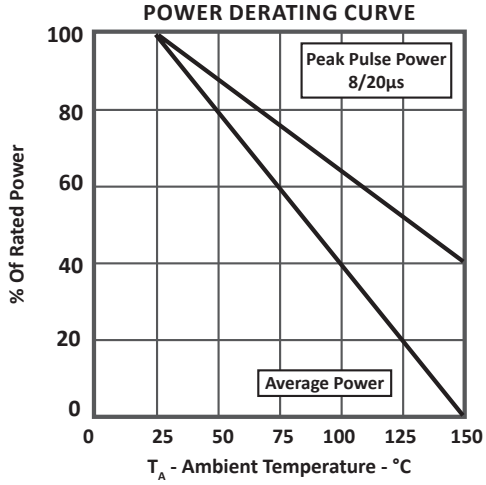
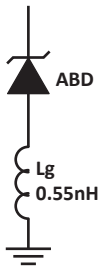


FIGURE 3
POWER DERATING CURVE



SPICE MODEL

FIGURE 1
SPICE MODEL FOR



ABD - Avalanche Breakdown Diode (TVS)
Lg - Lead Inductance

TABLE 1 - SPICE PARAMETERS

PARAMETER	UNIT	ABD(TVS)
BV	V	See Table 2
IBV	µA	1
C_{jo}	pF	See Table 2
I_s	A	See Table 2
Vj	V	0.6
M	-	0.33
N	-	1
R_s	Ohms	See Table 2
TT	s	1E-8
EG	eV	1.11

TABLE 2 - ABD SPECIFIC SPICE PARAMETERS

PART NUMBER	B_V(VOLTS)	C_{jo}(pF)	I_s (AMPS)	Rs(OHMS)
PSD05HP	6.0	880	1E-11	0.09
PSD10HP	11.0	500	1E-11	0.09
PSD12HP	13.3	440	1E-11	0.09

APPLICATION INFORMATION

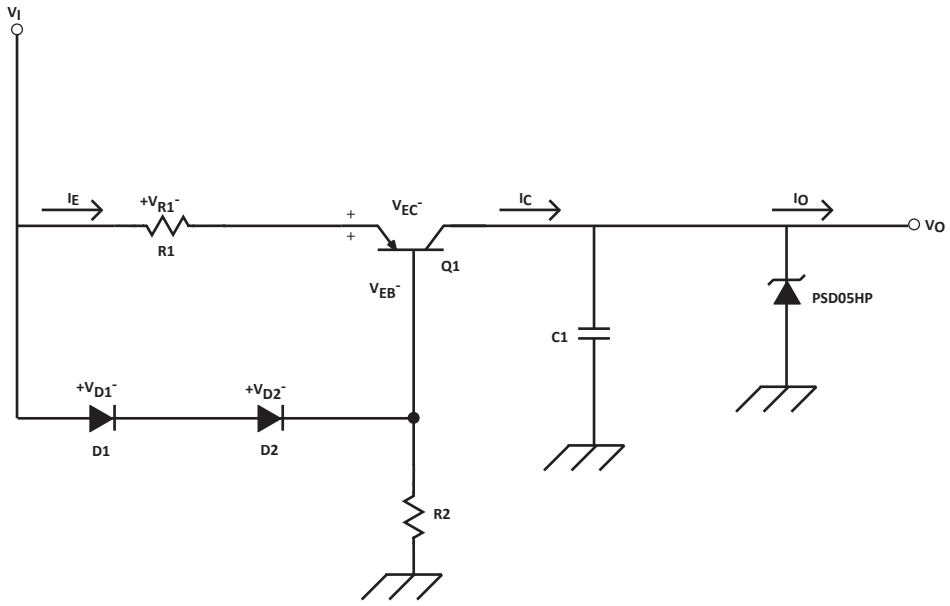


FIGURE 1 - USB BATTERY CHARGER APPLICATION

- One PSD05HP is placed on the output of the power regulator to protect the VBAT line from switching transients as well as EFT that may occur across the line.

CIRCUIT BOARD RECOMMENDATIONS

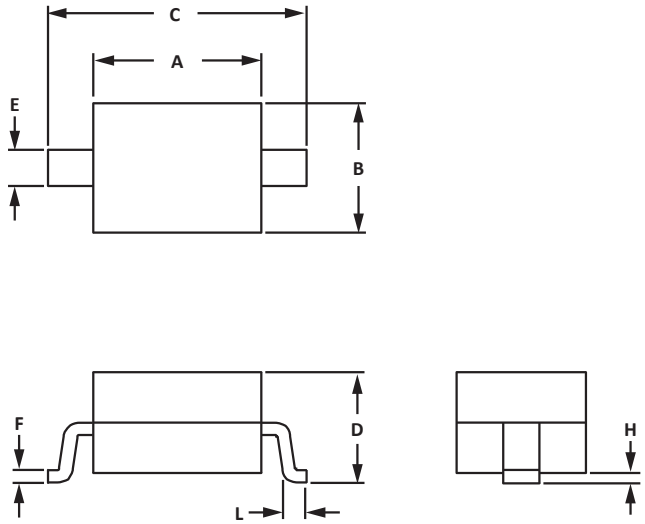
Circuit board layout is critical for electromagnetic compatibility protection. The following guidelines are recommended:

- The protection device should be placed near the input terminals or connectors, the device will divert the transient current immediately before it can be coupled into the nearby traces.
- The path length between the TVS device and the protected line should be minimized.
- All conductive loops including power and ground loops should be minimized.
- The transient current return path to ground should be kept as short as possible to reduce parasitic inductance.
- Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.

SOD-323 PACKAGE INFORMATION

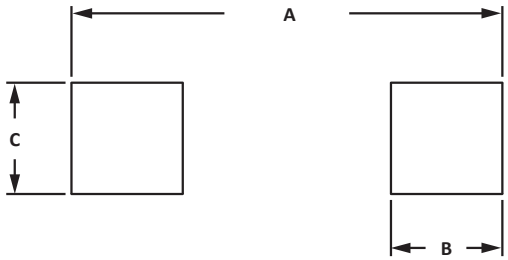
OUTLINE DIMENSIONS				
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.60	1.90	0.063	0.075
B	1.15	1.45	0.045	0.057
C	2.39	2.70	0.094	0.106
D	0.80	1.10	0.031	0.043
E	0.25	0.40	0.010	0.016
F	0.10	0.20	0.004	0.008
H	-	0.10	-	0.004
L	0.20	-	0.008	-

NOTES
1. Controlling dimension: millimeters.
2. Dimensioning and tolerances per ANSI Y14.5M, 1985.
3. Dimensions are exclusive of mold flash and metal burrs.

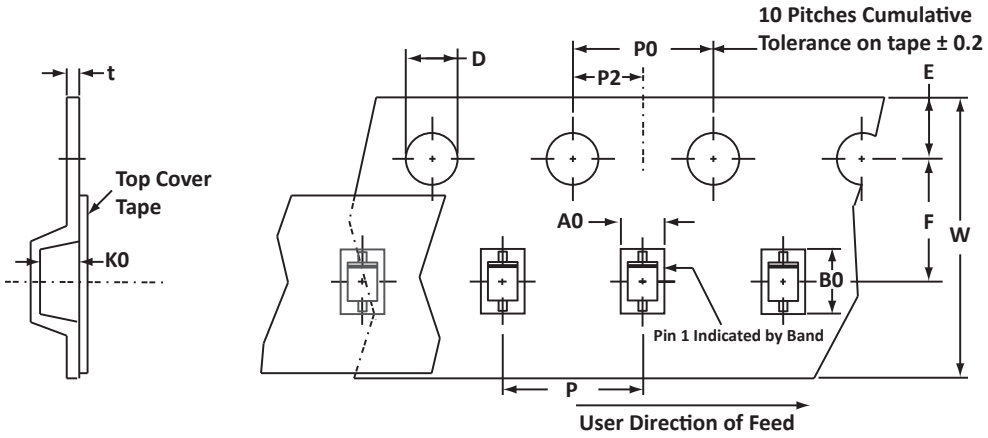


PAD LAYOUT DIMENSIONS				
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.87	3.12	0.113	0.123
B	0.66	0.91	0.026	0.036
C	0.66	0.91	0.026	0.036

NOTES
1. Controlling dimension: millimeters.



TAPE AND REEL



SPECIFICATIONS												
REEL DIA.	TAPE WIDTH	A0	B0	K0	D	E	F	W	P0	P2	P	tmax
178mm (7")	8mm	1.55 ± 0.10	2.90 ± 0.10	1.35 ± 0.10	1.50 ± 0.10	1.75 ± 0.10	3.50 ± 0.05	8.00 ± 0.30	4.00 ± 0.10	2.00 ± 0.05	4.00 ± 0.10	0.25

NOTES
1. Dimensions are in millimeters.
2. Surface mount product is taped and reeled in accordance with EIA-481.
3. Suffix - T7 = 7" Reel - 3,000 pieces per 8mm tape.
4. Marking on Part - marking code (see page 2), polarity band.

ORDERING INFORMATION					
BASE PART NUMBER (xx = Voltage)	LEADFREE SUFFIX	TAPE SUFFIX	QTY/REEL	REEL SIZE	TUBE QTY
PSDxxHP	N/A	-T7	3,000	7"	N/A
This device is only available in a Lead-Free configuration.					

COMPANY INFORMATION

COMPANY PROFILE

In business more than 25 years, ProTek Devices™ is a privately held semiconductor company. The company offers a product line of overvoltage protection and overcurrent protection components. These include transient voltage suppressor array (TVS arrays) avalanche breakdown diode, steering diode TVS array and electronics SMD chip fuses. These components deliver circuit protection in electronic systems from numerous overvoltage and overcurrent events. They include lightning; electrostatic discharge (ESD); nuclear electromagnetic pulses (NEMP); inductive switching; and electromagnetic interference (EMI) / radio frequency interference (RFI). ProTek Devices also offers LED wafer die for ESD protection and related high frequency products. ProTek Devices is ISO 9001:2015 certified.

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